

Data requirements for semiconductor die —

Part 5-3: Particular requirements and recommendations for die types — Minimally-packaged die

ICS 31.080

National foreword

This Published Document reproduces verbatim ES 59008-5-3:2001.
The UK participation in its preparation was entrusted to Technical Committee EPL/547, Known Good Die, which has the responsibility to:

- aid enquirers to understand the text;
- present to the responsible international/European committee any enquiries on the interpretation, or proposals for change, and keep the UK interests informed;
- monitor related international and European developments and promulgate them in the UK.

A list of organizations represented on this committee can be obtained on request to its secretary.

Cross-references

The British Standards which implement international or European publications referred to in this document may be found in the BSI Standards Catalogue under the section entitled “International Standards Correspondence Index”, or by using the “Find” facility of the BSI Standards Electronic Catalogue.

A British Standard does not purport to include all the necessary provisions of a contract. Users of British Standards are responsible for their correct application.

Compliance with a British Standard does not of itself confer immunity from legal obligations.

This Published Document, having been prepared under the direction of the Electrotechnical Sector Policy and Strategy Committee, was published under the authority of the Standards Policy and Strategy Committee on 05 December 2001

Summary of pages

This document comprises a front cover, an inside front cover, the ES title page, pages 2 to 8, an inside back cover and a back cover.

The BSI copyright date displayed in this document indicates when the document was last issued.

Amendments issued since publication

Amd. No.	Date	Comments